TOSHIBA

Date: April 27, 2021

Dear Sir/ Madam:

Notification of Change in Indication on Moisture-proof Bag

We greatly appreciate your continued business.

This is to notify you of our plan to make a change in label indication on moisture-proof bag used for our product supplied to you, which change will involve no change in product.

Details of the planned change are given in the following page.

If you have any questions or inquiry regarding this change, please inform our Sales representatives nearest you.

We appreciate your understanding and cooperation.

Yours faithfully,

H. Toyoda, Manager
Semiconductor Quality & Reliability Engineering Group II
Semiconductor Quality & Reliability Engineering Dept.
Semiconductor Quality Center
Semiconductor Div.
Toshiba Electronic Devices & Storage Corporation



1. Description of Change

Current label of moisture-proof bag	New moisture-proof bag label
(partly used for products manufactured	
outside Japan)	
- bearing English indication only	- bearing both Japanese and English indication in order
	to unify the domestic and overseas specifications
EXAMPLE A Construction of the set of the	注意: 表面実装型のブラスチックパッケージ製品については、吸湿した状態で放置されたり実装工程などの熟ストレスを 受けたりすると、製品の信頼性に影響を及ぼす可能性があります。した「の条件を守って使用ください。 開封後は、梱包時に貼り付ける「パーコードラベル」に記載した条件内での実装をお願いします。 防湿包装線の開封時に、温度インジケータの10%検知部が完全に茶色ではなく5%の部分が薄縁の場合、若しくは 有効期間が切れていた場合は使用する前に以下の条件を守って使用ください。 防湿包装線の開封時に、温度インジケータの10%検知部が完全に茶色ではなく5%の部分が薄縁の場合、若しくは 有効期間が切れていた場合は使用する前に以下の条件をやって少処理を実施願います。 ペーキング条件:125℃/20時間 ペーキング条件:125℃/20時間 ペーキング条件:20世界の表して、レーイが耐熱性かどうか確認してください (1) 必ず防湿包装袋よりトレイごと製品を取り出して、トレイが耐熱性かどうか確認してください (2) 耐熱性の場合はそのままペークしてください。 (3) 耐熱性でない場合は、耐熱性のある、静電気対策を施された容認などに製品を移し替えてペークしてください CAUTION: Comply with the following conditions for use of the plastic-packaged surface mount devices. The moisture absorbed in the devices may result in reliability degradation if left untreated or exposed to thermal stress during mounting. After opening this sealed moisture-barrier bag, mount the devices within the conditions described on a bar code label attached on each pack. Store the devices in this sealed moisture-barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 30degC/85%RH or lower. Use the devices in this sealed moisture barrier bag at 0 devices the ordine the following conditions. Bake the devices the original trays to bake the devices. (

2. Scheduled Date of Change

New label indication will be applied to product lot subjected to packing operation from June 1, 2021 onward.

3. Products Affected:

TOSHIBA PART NUMBER	
TB67H401FTG(O,EL)	TB67S289FTG(O,EL)
TB67H420FTG(O,EL)	TB67S508FTG(Z,EL)
TB67S128FTG(O,EL)	TMPM36BF10FG(DBB)
TB67S179FTG(O,EL)	TMPM36BFYFG(DBB)
TB67S249FTG(O,EL)	TMPM462F15FG(BDBB)
TB67S279FTG(O,EL)	TMPM4G9F15FG(DBB)